SCI7500F0A

Contents

OVERVIEW	6-1
TERMINAL FUNCTIONS	6-4
EXPLANATIONS OF FUNCTIONS	6-8
ELECTRICAL CHARACTERISTICS	6-15
EXAMPLE OF CONNECTIONS (REFERENCE)	6-20
EXTERNAL DIMENSIONS (REFERENCE)	6-22
EXTERNAL SHAPE OF THE CHIP (SCI7500D0A)	6-23
COORDINATES OF RESPECTIVE PAD CENTERS	6-24

OVERVIEW

Description

The SCI7500F0A is a four-line simultaneous selection method MLS (Multi Line Selection) drive power supply IC for driving liquid crystal displays. Using its CMOS charge pump-type high-efficiency voltage converter circuit, the chip is able to generate all the bias voltages required for the four-line MLS drive based on a single 3.0 V power supply input.

When a system is structured from column (segment) drivers such as the SED1580, row (common) drivers such as the SED1751, and this IC, this structure is able to produce a module with extremely low power consumption when compared to a conventional drive method.

Moreover, even greater power conservation is possible when combined with an LCD controller that can pause data transmission (a controller such as the SED1360).

Features

- Power Supply Voltage:
- 2.4 V to 3.6 V single-input power supply • Low Consumption Current: 340 μ A (in 6 × step-up mode, TYP)
- Standby Current:
- High Voltage Conversion Efficiency: 88% (6 × step-up mode, TYP)
- Generates all bias voltages required for 4-line MLS driving. An external contrast adjustment function can also be attached.
- Equipped with an internal charge pump-type DC/DC voltage converter circuit. Depending on the terminal settings, the chip can be switched between $5 \times \text{step-up}$ (compatible with 1/200 duty) and $6 \times$ step-up (compatible with 1/240 duty).

5 uA (MAX)

- Built-in electric charge discharging circuit for the liquid crystal drive current (VL).
- Internal "power off" function using an external signal (XSLP).
- Equipped internally with a liquid crystal drive polarity reverse signal generator circuit.
- The terminal settings can be used to set the range of time for the polarity reversal to 2H to 17H.
- Recommended panel size: VGA, 6.3" or less
- Product being shipped in QFP form (QFP12-48 pin) SCI7500F0A
- Product being shipped in chip form SCI7500D0A
- This product not designed for resistance to radiation.

Block Diagram

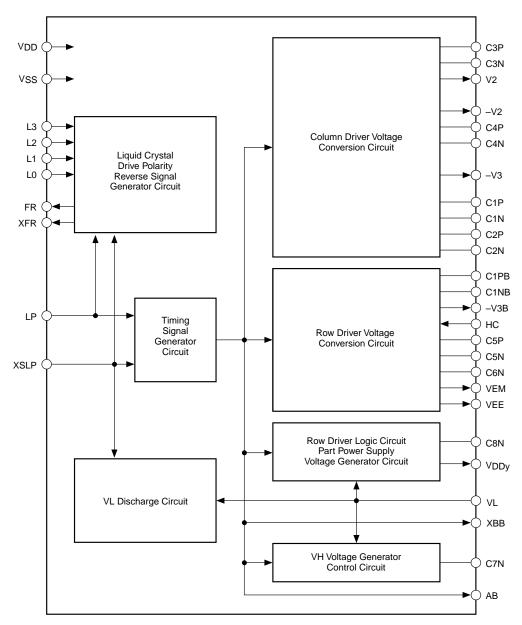


Figure 1: Block Diagram

Explanation of Block Diagram

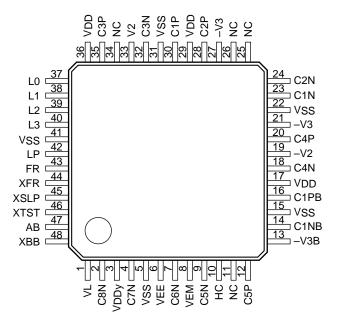
• Liquid Crystal Drive Polarity Reverse Signal Generator Circuit

This circuit generates the reverse polarity signal FR from the 1H period pulse signal LP. Pins L0 to L3 can be used to set the polarity reversal interval to 2H to 17H. Moreover, so that it will be possible to drive the top and bottom screens in a 2-screen drive panel in opposite phases, this IC outputs two signals with opposite polarities of each other (FR, XFR).

- Timing Signal Generator Circuit This circuit generates the clock for the charge pump from the 1H period pulse signal LP. When the display off control signal XSLP is set to the Vss level, the clock stops and the voltage converter operation stops.
- Column Driver Voltage Conversion Circuit
 - This circuit generates the V2, -V2, and -V3 voltage levels required for column driving.
- Row Driver Voltage Conversion Circuit This generates the voltage (VEE) required for generating the power supply voltages (VH, VL) required for the row drivers. Using VDD as the reference, this generates either a 5 × or 6 × voltage level in the negative direction relative to the input power supply voltage. A terminal can be used to switch between the step-up modes. The contrast adjustment function is performed through the use of an external emitter follower circuit to adjust VEE to generate VL.
- Row Driver Logic Circuit Part Power Supply Voltage Generator Circuit This generates the power supply voltage (VDDy) required by the row driver logic circuit part. This generates a voltage that is higher than the voltage level VL by an amount equal to VDD–VSS.
- VH Voltage Generator Control Circuit This is a circuit for generating the power supply voltage (VH) required for the row driver. The VH voltage can be generated by an external MOS transistor and this circuit.
- VL Discharge Circuit At power off or display off, this circuit discharges the charge remaining on the row driver negative voltage level-side power supply voltage terminal (VL).

TERMINAL FUNCTIONS

Terminal Layout Diagram



Terminal No.	Terminal Name	Terminal No.	Terminal Name	Terminal No.	Terminal Name	Terminal No.	Terminal Name
1	VL	13	—Vзв	25		37	L0
2	C8N	14	C1NB	26	_	38	L1
3	Vddy	15	Vss	27	-V3	39	L2
4	C7N	16	C1PB	28	C2P	40	L3
5	Vss	17	Vdd	29	Vdd	41	Vss
6	Vee	18	C4N	30	C1P	42	LP
7	C6N	19	-V2	31	Vss	43	FR
8	VEM	20	C4P	32	C3N	44	XFR
9	C5N	21	-V3	33	V2	45	XSLP
10	HC	22	Vss	34		46	XTST
11		23	C1N	35	C3P	47	AB
12	C5P	24	C2N	36	Vdd	48	XBB

Explanation of Terminals Liquid Crystal Drive Polarity Reverse Signal Generator Circuit

Terminal Name	I/O	SCI7500FoA Terminal Number	SCI7500D _{0A} PAD Number	Function
L0 to L3	I	37 to 40	1 to 4	Polarity reverse time setting terminals. These are the input terminals for setting the polarity reverse time. The time can be set in the range of 2H to 17H.
FR	0	43	7	Polarity reverse forward phase signal terminal. This terminal outputs the signal that is generated by the polarity reverse signal generating circuit.
XFR	0	44	8	Polarity reverse signal reverse phase terminal. This outputs the signal that is in the reverse phase from the polarity reverse forward phase signal terminal.

Timing Signal Generator Circuit

Terminal Name	I/O	SCI7500F _{0A} Terminal Number	SCI7500D _{0A} PAD Number	Function
LP	I	42	6	Display data latch pulse input terminal. This is the input terminal for generating the charge pump clock and the polarity reverse signal. It is necessary to input into this terminal a pulse signal with a period of 1H.
XSLP	I	45	9	The display off control signal terminal. Setting this terminal to the VSS level stops the clock and stops the operations of the voltage converter.

Column Driver Voltage Conversion Circuit

Terminal Name	I/O	SCI7500F _{0A} Terminal Number	SCI7500D _{0A} PAD Number	Function
C3P	(O)	35	43	The positive-side connection terminal for the flying capacitor CP3 for generating the V ₂ output voltage.
C3N	(O)	32	41	The negative-side connection terminal for the flying capacitor CP3 for generating the V2 output voltage.
V2	0	33	42	V2 output voltage terminal.
C4P	(O)	20	31	The positive-side connection terminal for the flying capacitor CP4 for generating the $-V_2$ output voltage.
C4N	(O)	18	29	The negative-side connection terminal for the flying capacitor CP4 for generating the $-V_2$ output voltage.
-V2	0	19	30	-V2 output voltage terminal.
C1P	(O)	30	39	The positive-side connection terminal for the flying capacitor CP1 for generating the $-V_3$ output voltage.
C1N	(O)	23	34	The negative-side connection terminal for the flying capacitor CP1 for generating the $-V_3$ output voltage.
C2P	(O)	28	37	The positive-side connection terminal for the flying capacitor CP2 for generating the $-V_3$ output voltage.
C2N	(O)	24	35	The negative-side connection terminal for the flying capacitor CP2 for generating the $-V_3$ output voltage.
-V3	0	21, 27	32, 36	-V ₃ output voltage terminal.

Terminal Name	I/O	SCI7500F _{0A} Terminal Number	SCI7500D _{0A} PAD Number	Function
C1PB	(O)	16	27	The positive-side connection terminal for the flying capacitor CP1B and CP8 for generating the $-V_{3B}$ output voltage.
C1NB	(O)	14	25	The negative-side connection terminal for the flying capacitor CP1B for generating the $-V_{3B}$ output voltage.
—Vзв	0	13	24	The negative V _{3B} output voltage terminal. This is an output terminal equipped as the middle voltage level for generating the VEE output voltage.
нс	I	10	22	The step-up mode select terminal. When this terminal is tied Vss, then the chip is put into 5 X step-up mode. However, when it is connected to $-3B$, the chip is set to 6 X step-up mode.
C5P	(O)	12	23	The positive-side connection terminal for the flying capacitor CP5 and CP6 for generating the VEM output voltage.
C5N	(O)	9	21	The negative-side connection terminal for the flying capacitor CP5 for generating the VEM output voltage.
VEM	0	8	20	The VEM output voltage terminal. This is an output terminal equipped as the middle voltage level for generating the VEE output voltage.
C6N	(O)	7	19	The negative-side connection terminal for the flying capacitor CP6 for generating the VEE output voltage. (The positive-side of CP6 is C5P.)
Vee	0	6	18	The VEE output voltage terminal. By changing the HC terminal interconnection method, it is possible to switch between the 5-level step-up mode and the 6-level step-up mode.

Row Driver Voltage Conversion Circuit

Common Driver Logic Circuit Part Power Supply Voltage Generator Circuit

Terminal Name	I/O	SCI7500F _{0A} Terminal Number	SCI7500D _{0A} PAD Number	Function
C8N	(O)	2	14	The negative-side connection terminal for the flying capacitor CP8 for generating the VDDy output voltage. The positive connection terminal for CP8 is the same as C1PB.
Vddy	0	3	15	The row driver logic circuit part power supply output terminal. This generates the power supply voltage required for the row driver logic circuit part. The output is higher than the VL level in the positive direction by an amount equal to the difference between VDD and Vss.

VH Voltage Generator Control Circuit

Terminal Name	I/O	SCI7500F _{0A} Terminal Number	SCI7500D _{0A} PAD Number	Function
AB	0	47	11	The V _H output voltage generator clock terminal A. This is the clock output terminal for the external N-channel MOS transistor control.
ХВВ	0	48	12	The V _H output voltage generator clock terminal B. This is the clock output terminal for the external P-channel MOS transistor control.
C7N	(O)	4	16	The negative-side connection terminal for the flying capacitor CP7 for generating the VH output voltage. The positive-side connection terminal corresponds to the external transistor.

VL Discharge Circuit

Terminal Name	I/O	SCI7500FoA Terminal Number	SCI7500D _{0A} PAD Number	Function
VL	I	1	13	This is the row driver negative voltage level power supply voltage terminal. The VL signal that is used to adjust the contrast is input to this terminal. This serves as the power supply for the VH voltage generator control circuit. XSLP operates the discharge circuit at the VSS level.

The Test Circuit

Terminal Name	I/O	SCI7500F _{0A} Terminal Number	SCI7500D _{0A} PAD Number	Function
XTST	I	46	10	This is a test terminal. Insure that this terminal is always tied to the Vod level.

Power Supply Terminals <Note 1>

Terminal Name	I/O	SCI7500FoA Terminal Number	SCI7500D _{0A} PAD Number	Function
Vdd	I	17, 29, 36 *1	28, 38 44 *1	Input power supply terminals (positive).
Vss	I	5, 15, 22, 31, 41 *1	5, 17, 26 33, 40 *1	Input power supply terminals (negative).

Note: *1 Please connect these power supply terminals externally.

EXPLANATIONS OF FUNCTIONS

Overview of Operation

The SCI7500F0A is a power supply IC for operating the 4-line simultaneous selection method MLS (Multi Line Selection) driver LCDs. Using its CMOS charge pump-type high-efficiency voltage converter circuit, this chip can produce all of the bias voltages necessary for a 4-line MLS driving based on a single 3.0 V power supply.

The voltage levels produced are as follows:

- The liquid crystal drive power supply voltages required for the column drivers (V3 = VDD, V2, VC = VSS, -V2, -V3).
- The liquid crystal drive power supply voltages required for the row drivers (VH, VC = VSS, VL).
- The power supply voltages for the logic circuits of the row driver (VDDy).

However, the row driver low voltage-side power supply voltage (VL) requires an external bipolar transistor for adjusting the contrast. Moreover, external MOS transistors (2SK***, 2SJ***) are required for generating the row driver high-level power supply voltage (VH).

Depending on a terminal setting, the chip can switch between 6 X step-up mode and 5 X step-up mode, with 1/240 duty and 1/200 duty, respectively. Consequently, it is possible to obtain the required voltages with maximum efficiency.

An example of a system structure diagram for the power supply interconnections is given below:

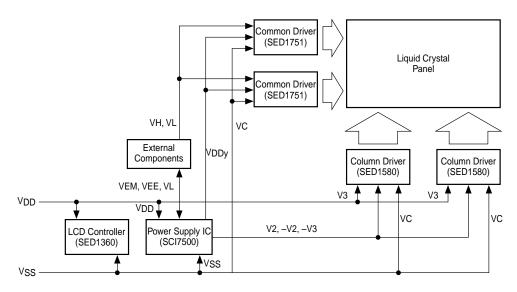
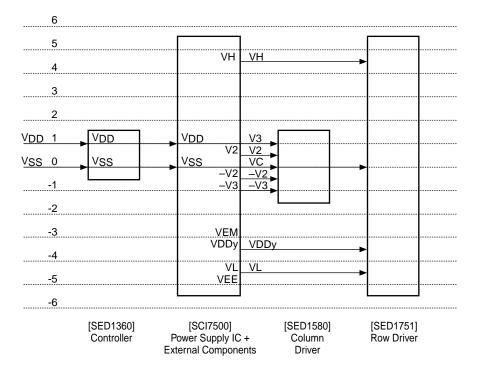


Figure 2: The System Configuration



The relationships between voltage levels in the system shown in Figure 2 are given in the table below.

Figure 3: The Relationships Between Voltages Within the System (in 6 × step-up mode)

The logical formulas for each of the voltage levels is as given below:

When in 6 × s (when HC is con		When in $5 \times$ step-up mode (when HC is connected to Vss).		
Logical Formula	Voltage level when VDD = 3.0V and Vss = 0V	Logical Formula	Voltage level when VDD = 3.0V and Vss = 0V	
$VH = -VL = 5 (VDD - VSS) - \alpha$	15.0–α	$V_{H} = -V_{L} = 4 (V_{DD} - V_{SS}) - \alpha$	12.0–α	
V3 = VDD-VSS	3.0	V3 = VDD-VSS	3.0	
V ₂ = 1/2 (VDD-VSS)	1.5	V2 = 1/2 (VDD-VSS)	1.5	
Vc = Vss	0	Vc = Vss	0	
$-V_2 = -1/2$ (VDD-VSS)	-1.5	$-V_2 = -1/2$ (VDD-VSS)	-1.5	
$-V_3 = -V_{3B} = -(V_{DD} - V_{SS})$	-3.0	$-V_3 = -V_{3B} = -(V_{DD} - V_{SS})$	-3.0	
Vem = -3 (Vdd-Vss)	-9.0	$V_{EM} = -2 (V_{DD} - V_{SS})$	-6.0	
$VDDy = -4 (VDD-VSS) + \alpha$	-12.0 + α	$V_{DDy} = -3 (V_{DD} - V_{SS}) + \alpha$	-9.0 + α	
$V_L = -5 (V_{DD} - V_{SS}) + \alpha$	-15.0 + α	$VL = -4 (VDD - VSS) + \alpha$	-12.0 + α	
Vee = -5 (Vdd-Vss)	-15.0	VEE = -4 (VDD-VSS)	-12.0	

Where $\alpha = \text{variable} \ge 0$ (contrast adjustment)

The Liquid Crystal Drive Polarity Reverse Signal Generator Circuit

This circuit produces the polarity reverse signal from the 1H period pulse signal LP. Terminals L0 to L3 can be used to set the polarity reversed period in the range of 2H to 17H. So that the upper and lower screens can be driven in mutually opposite phases when a 2-screen drive panel is used, this IC outputs two signals with mutually opposing polarities (i.e. with opposite phases) from the FR and the XFR terminals. The timing of the output transitions is synchronized with the falling edge of the LP signal.

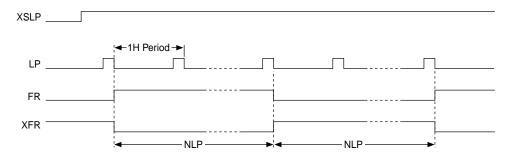


Figure 4: LP and FR Signal Timing Diagram

The relationship between the NLP during the polarity reversed interval and the settings of terminals L0 to L3 is as shown below:

Terminal	Terminal Settings While Polarity is Reversed					Function		
L3	L2	L1	L0	Time	NLP			
		0	0	17H	LP Signal	17th pulse		
	0	0	1	2H	LP Signal	2nd pulse		
	0	1	0	3H	LP Signal	3rd pulse		
		I	1	4H	LP Signal	4th pulse		
0		0	0	5H	LP Signal	5th pulse		
		0	1	6H	LP Signal	6th pulse		
	1	4	0	7H	LP Signal	7th pulse		
		1		1	8H	LP Signal	8th pulse	
		0	0	9H	LP Signal	9th pulse		
	0	0	1	10H	LP Signal	10th pulse		
	0	1	0	11H	LP Signal	11th pulse		
1			1	12H	LP Signal	12th pulse		
1		0	0	13H	LP Signal	13th pulse		
	1	0	1	14H	LP Signal	14th pulse		
		1	0	15H	LP Signal	15th pulse		
			1	16H	LP Signal	16th pulse		

The Timing Signal Generator Circuit

This generates the clock for the charge pump from the 1H period pulse signal LP. When the display off control signal XSLP is set to Vss, this clock stops and the IC voltage converter operation halts. The VH output voltage generator clocks AB and XBB are also produced by this circuit.

Input Signal XSLP	
Input Signal LP	
Output Signal AB	
Output Signal XBB	

Figure 5: The AB and XBB Signal Output Timing

The Voltage Converter Circuit

The voltage converter circuit comprises a CMOS charge pump-type DC/DC converter. The relational diagram of the voltage converter circuits within this IC is as shown below. The numbers within parentheses in the diagram correspond to the number in "Figure 1: Block Diagram."

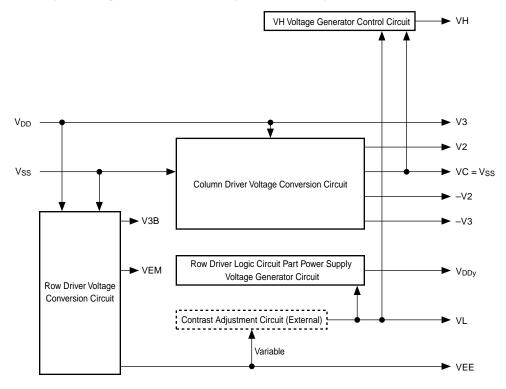


Figure 6: A Relational Diagram of the Voltage Converter Circuits

When in 6 × st (when HC is conn		When in 5 \times step-up mode (when HC is connected to VSS).		
Logical Formula	Voltage level when VDD = 3.0V and VSS = 0V	Logical Formula	Voltage level when VDD = 3.0V and VSS = 0V	
VH = -VL = 5 (VDD-VSS)-a	15.0–α	$V_{H} = -V_{L} = 4 (V_{DD} - V_{SS}) - \alpha$	12.0–α	
V3 = VDD-VSS	3.0	V3 = VDD-VSS	3.0	
V2 = 1/2 (VDD-VSS)	1.5	V2 = 1/2 (VDD-VSS)	1.5	
Vc = Vss	0	Vc = Vss	0	
-V ₂ = -1/2 (V _{DD} -V _{SS})	-1.5	$-V_2 = -1/2$ (VDD-VSS)	-1.5	
$-V_3 = -V_{3B} = -(V_{DD} - V_{SS})$	-3.0	$-V_3 = -V_{3B} = -(V_{DD} - V_{SS})$	-3.0	
Vem = -3 (Vdd-Vss)	-9.0	$V_{EM} = -2 (V_{DD} - V_{SS})$	-6.0	
$VDDy = -4 (VDD - VSS) + \alpha$	-12.0+ α	$V_{DDy} = -3 (V_{DD} - V_{SS}) + \alpha$	-9.0 + α	
$V_L = -5 (V_{DD} - V_{SS}) + \alpha$	-15.0+ α	$VL = -4 (VDD - VSS) + \alpha$	-12.0 + α	
VEE = -5 (VDD-VSS)	-15.0	VEE = -4 (VDD-VSS)	-12.0	

Logical Formulas for the Various Voltage Levels

Where $\alpha = variable \ge 0$ (contrast adjustment)

The capacitors for the charge pump can be of two different types: the flying capacitors which transition between a charged state and a discharged state, and the storage capacitor that stores charge. The clock that controls the state changes in the flying capacitors is generated by the timing signal generator circuit from the display data latch pulse input terminal LP. The operating frequency f sw of the flying capacitor is calculated as follows:

 $fsw = 1/(2 \times t_{CLP})$ Where t CLP is the LP frequency.

The voltage logic that is biased by both ends of the flying capacitors and storage capacitors is as shown below: (Reference "10. Example of Connections (Reference)" regarding recommended capacitance values and connection methods for the capacitors.)

Flying Capacitors and Storage Capacitors

Capacitor Name		Voltage logic fo both ends of	Column side/	
INAI	6 × step-up mode		$5 \times \text{step-up mode}$	Row side
	CP1	VDD-VSS	VDD-VSS	
	CP2	VDD-VSS	VDD-VSS	Column Cide
	CP3	1/2 (VDD-VSS)	1/2 (VDD-VSS)	Column Side
Eb dia a	CP4	1/2 (VDD-VSS)	1/2 (VDD-VSS)	
Flying	CP1B	Vdd-Vss	VDD-VSS	
Capacitor	CP5	2 (VDD-Vss)	VDD-VSS	
	CP6	2 (VDD-VSS)	2 (VDD-VSS)	Row side
	CP7	5 (Vdd-Vss) -α	4 (VDD-VSS) -α	
	CP8	5 (Vdd-Vss) -α	4 (VDD-VSS) -α	
	CB1	Vdd-Vss	VDD-VSS	
	CB3	1/2 (VDD-VSS)	1/2 (VDD-VSS)	Column side
	CB4	1/2 (VDD-VSS)	1/2 (VDD-VSS)	
Charasta	CB1B	VDD-VSS	VDD-VSS	
Storage	CB5	2 (VDD-VSS)	VDD-VSS	
Capacitor	CB6	2 (VDD-VSS)	2 (VDD-VSS)	Devusida
	CB7	5 (VDD–VSS) – α	4 (VDD-VSS) -α	Row side
	CB8	Vdd-Vss	VDD-VSS	
	CVL	5 (Vdd-Vss) -α	4 (VDD-VSS) -α	

Where α = variable \geq 0 (contrast adjustment)

In the column driver voltage converter circuit either flying capacitor CP1 or CP2 can be omitted. When the panel is smaller than a 6.3 inch VGA panel, or if one wishes to sacrifice image quality to save cost, one may consider this omission; however, the output impedance will increase and will be outside of what is indicated in "Electrical Characteristics," and thus we recommend that you experimentally confirm the structure for each application.

Switching between the step-up modes in the row driver voltage converter circuits can be done by setting the HC terminal. When the HC terminal is connected to -V3B, then the system will be in $6 \times$ step-up mode, but when the HC terminal is connected to the Vss terminal, then the system will be in $5 \times$ step-up mode. Furthermore, by connecting the -V3 terminal to the -V3B terminal, it is possible to omit the flying capacitor CP1B and storage capacitor CP1B. However, when these capacitors are omitted, the output impedance will increase and will be outside of what is indicated in "Electrical Characteristics," and thus we recommend that you experimentally confirm the structure for each application.

The Contrast Adjustment Circuit

The row driver negative voltage-side power supply voltage VL can be adjusted and generated by an external emitter follower circuit using VEE. The contrast adjustment function is shown in the circuit connection example below:

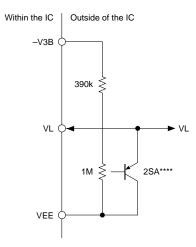


Figure 7: Contrast Adjustment Circuit

The VH Voltage Generator Control Circuit

The row driver positive voltage-side power supply voltage VH can be generated from this circuit and the VH output voltage generator clocks AB, XBB, and external components. This is shown in the circuit connection example below.

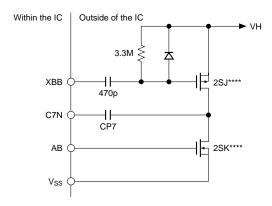


Figure 8: Example of Circuit Connections for Generating the VH Voltage

The VL Discharge Circuit

When XSLP is put to the Vss level, the VL discharge circuit within the IC is triggered, and residual charge at the row driver negative voltage-side power supply voltage terminal VL is discharged to the Vss level. The VL voltage adjusted for the contrast must be input to the VL terminal. (See "The Contrast Adjustment Circuit.")

The VH Discharge Circuit

When XSLP is put to the Vss level, the residual charge at the row driver positive voltage-side power supply terminal VH can be discharged to the Vss level through an external MOS transistor. An example circuit connection is shown below.

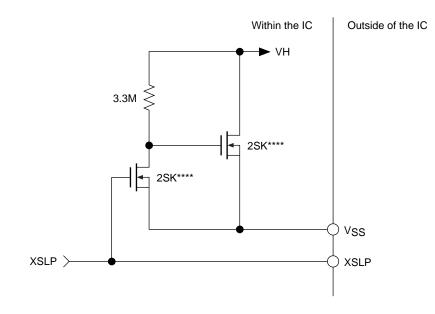


Figure 9: The VH Discharge Circuit

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ELECTRICAL CHARACTERISTICS

The Absolute Maximum Ratings

					Vss = 0V
ltem	Signal	Rated	Value	Units	Notes
item	Signal	Minimum	Maximum	Units	Notes
Input power supply voltage 1	Vdd		3.7	V	VDD terminal
Input power supply voltage 2	VL	VEE-0.3	0.3	V	VL terminal
Input terminal voltage	VI	-0.3	Vdd + 3.0	V	The L3 to L0, LP, XSLP, and XTST terminals
Input current	IDD	—	10	mA	Vdd, Vl
Output current 1	IV2	—	6	mA	V2 terminal
Output current 2	I-V2	—	6	mA	-V2 terminal
Output current 3	I-V3	_	5	mA	-V3 terminal
Output current 4	I VEE		1	mA	VEE terminal
Output current 5	I VDDy		0.1	mA	VDDy terminal
Allowable loss	Pd		100	mW	Ta ≤ 55 °C
Operating temperature	Topr	-30	85	°C	—
Storage temperature	Tstg	-55	150	°C	_
Soldering temperature and time	Tsol	—	260 imes 10	$^{\circ}C \times S$	At the lead

Notes: *1 Do not apply a voltage from the outside to the output terminals nor to the capacitor connection terminals.

Notes: *2 Operating failures and/or permanent damage may occur if this chip is used under conditions exceeding the absolute maximum ratings listed above. Moreover, the reliability of this chip may be dramatically compromised even if the chip continues to function normally for a time.

DC Characteristics

		Standard	connections <n< th=""><th>ote 1>, Ll</th><th>P period</th><th>$= 69 \mu s, 1$</th><th>LP widt</th><th>$h = 1 \mu s.$</th></n<>	ote 1>, Ll	P period	$= 69 \mu s, 1$	LP widt	$h = 1 \mu s.$
ltom	Cumhal	Derem	Parameters		Standards		Units	Notes
Item	Symbol	Param	elers	Min	Тур	Max	Units	Notes
Input power supply voltage	Vdd	_		2.4	3.0	3.6	V	—
Input power supply voltage	VL	_		VEE+0.6	_	-V3	V	—
High level input voltage	Vін	Applicable terminals XSLP, L0 to L3, XT		0.8Vdd	—	Vdd	V	—
Low level input voltage	VIL	$V_{DD} = 2.4 \text{ to } 3.6 \text{V}$	51	0	—	0.2Vdd	V	—
Input leakage current	Ilin	$\label{eq:VSS} \begin{array}{l} Vss \leq VI \leq Vdd, \\ Vdd = 2.4 \text{ to } 3.6 V \end{array}$		-0.5	—	0.5	μΑ	—
V2 output	V2	lo = 2mA	VDD = 2.4V	1.148	_	1.2	V	—
voltage	V2	(to Vss)	VDD = 2.7V	1.298	—	1.35		
-V2 output	-V2	lo = 2mA	VDD = 2.4V	-1.2	—	-1.120	V	2
voltage	-V2	(from Vss)	VDD = 2.7V	-1.35	—	-1.272		
–V3 output	-V3	lo = 1mA	VDD = 2.4V	-2.4	_	-2.340	V	2
voltage	-V3	(from Vss)	VDD = 2.7V	-2.7	_	-2.644		
VEE output	VEE	lo = 0.4mA	VDD = 2.4V	-12.0	_	-11.2	V	—
voltage	VEE	(from Vss)	VDD = 2.7V	-13.5	—	-12.7		
VDDy output	Vddy	lo = 0.02mA	VDD = 2.4V	VL + 2.33	_	VL + 2.40	V	—
voltage	VDDy	(to VL)	VDD = 2.7V	VL + 2.63	—	VL + 2.70		
Output resistor 1	Ron1	Applicable terminal: C7N	VDD = 2.4V	—	_	16	Ω	3
resistor i		Iон = -0.2mA	VDD = 2.7V	—	—	15		
Output	Ron2	Applicable terminal: C7N	VDD = 2.4V	_	_	21	Ω	3
resistor 1		lон = 0.2mA	VDD = 2.7V	—	—	20		
High level output voltage	Vон	Applicable terminals:	Іон = −20μА	Vdd-0.1	_	Vdd	V	_
Low level output voltage	Vol	XBB, AB, FR, XFR VDD = 2.4 to 3.6V	Ιοι = 20μΑ	0	—	0.1	V	—
Consumption	IOPR5	$5 \times \text{step-up}$, no load VDD = 3.0 V		—	250	330	μA	—
Current	IOPR6	$6 \times step-up$, no load	6 × step-up, no load VDD = 3.0V		340	470	μA	—
Static current	la	VDD = 2.4 to 3.6V, X	VDD = 2.4 to 3.6V, XSLP = 0V		_	5	μA	—
Step-up power converter efficiency	Peff	$6 \times \text{step-up}, V_{DD} = 3.0V$ The load conditions were as follows: $V_2: Io = 2mA$ $-V_2: Io = 2mA$ $-V_3: Io = 1mA$ $V_4: Io = 0.4mA$ $V_5: Io = 0.02mA$		_	88	_	%	_

When not otherwise specified: $Ta = -30^{\circ}C$ to $+85^{\circ}C$, Vss = 0V, $6 \times$ step-up, VL = VEE + 0.6V, Standard connections <Note 1>, LP period = 69µs, LP width = 1µs.

Notes 1. For standard connections, see "Example of Connections (Reference)."

2. Measured in a state where negative charges were not applied to -V2 and -V3 simultaneously.

3. The measurement circuits and timing of the output resistance 1 RON1, and output resistance 2 RON2 are as shown below.

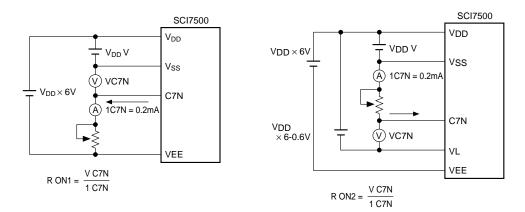
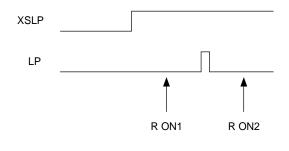
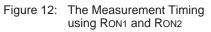




Figure 11: The RON2 Measurement Circuit



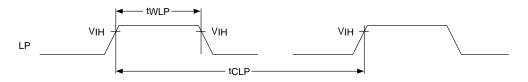


AC Characteristics

The AC test parameters:

- Input voltage level: VIH = 0.8 VDD V
- VIL = 0.2 VDD V
- Input signal rise time: Tr = max 10 ns
 Input signal fall time: Tf = max 10 ns
 - $V_{DD} = 2.4 \text{ to } 3.6 \text{ V}$ $V_{SS} = 0 \text{ V}$ $T_a = -30 \text{ to } 85 \text{ °C}$

Input Timing Characteristics

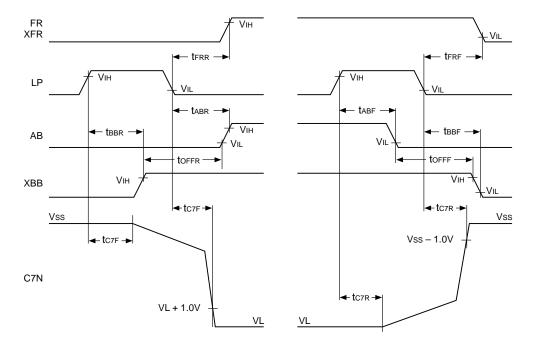


ltarra	Currents of		Ratings		Linite	Nataa
Item	Symbol	Min	Тур	Max	Units	Notes
LP Period	t CLP	50	65 to 90	125	μs	
LP Pulse Width	twlp	70		2000	ns	*1

Note *1 While the chip continues to function with LP pulse widths in excess of 2000 ns, the wider the LP pulse width, the higher the output impedance of the various output voltages. For this IC, although we are recommending inputting of LP signals through the LP pin as the basic clock, inputting of other signals through the LP pin will also provide the same characteristics as far as the signals being input can satisfy the above specifications.

(Reference) LP Period

Frame Frequency	Duty	LP Period
40	1/200	125 μs
60	1/200	83 µs
60	1/240	69 µs
80	1/240	52 μs



Output Timing Characteristics

LP pulse width = 1μ s, 6 X	step-up voltag	ge, VL = VE	E + 0.6V, S	tandard Conn	ections

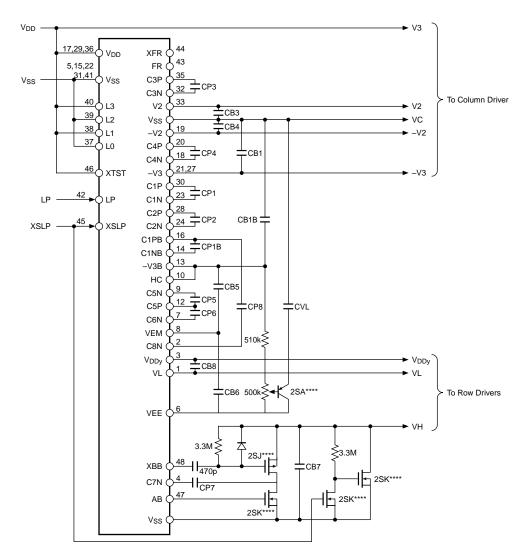
ltem	Signal	Applicable	Load	Rated Values		Units
Item	Signal	Terminals	Conditions	Min	Max	Units
FR signal rise delay time	t FRR	FR, XFR		330	3300	ns
FR signal fall delay time	t FRF	FR, XFR	C∟ = 50pF	330	3300	ns
AB signal rise delay time	t abr	AB		230	2000	ns
AB signal fall delay time	t ABF	AB		180	1900	ns
XBB signal rise delay time	t BBR	XBB		130	1100	ns
XBB signal fall delay time	t BBF	XBB	*2	280	3200	ns
Rising edge output phase differential time	toffr	AB, XBB		1000	2400	ns
Falling edge output phase differential time	tofff	AB, XBB		1000	2200	ns
C7N signal falling edge delay time	tc7F	C7N	*3	270	2400	ns
C7N signal rising edge delay time	tc7R	C7N	3	490	3800	ns

*2 When 2SJ185, 2SK1399 (manufactured by NEC) are used.*3 With a load with standard connections. Note

Note

EXAMPLE OF CONNECTIONS (REFERENCE)

Standard Connections for the $6 \times$ step-up mode.

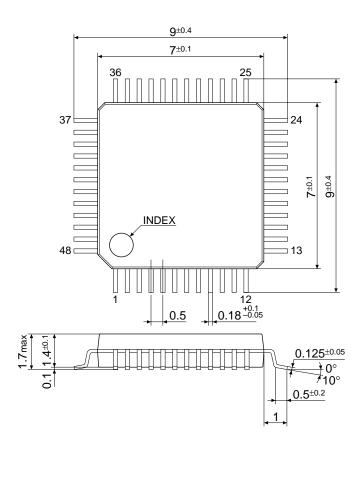


Capacitor Name	Capacitance Value (µF)	Capacitor Name	Capacitance Value (µF)
CP1	4.7	CB1	4.7
CP2	4.7	CB3	4.7
CP3	4.7	CB4	4.7
CP4	4.7	CB5	1.0
CP5	1.0	CB6	1.0
CP6	1.0	CB7	1.0
CP7	1.0	CB8	0.1
CP8	0.1	CB1B	4.7
CP1B	4.7	CVL	1.0

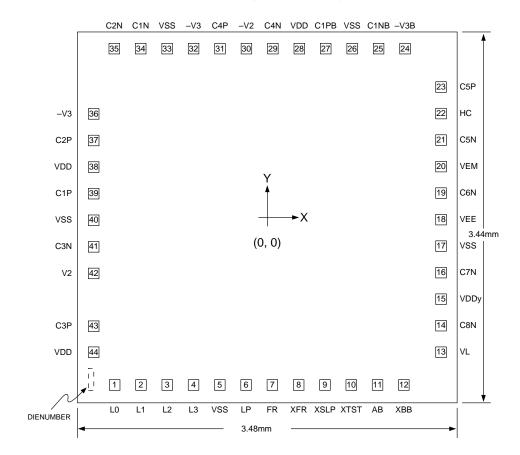
The capacitance values for the capacitors are the recommended value for a 6.3 inch VGA liquid crystal panel. The characteristics shown in "Electrical Characteristics" are the characteristics obtained when capacitors with the values shown above are used. Consequently, while one may consider reducing the capacitance values of these capacitors when a liquid crystal panel smaller than a 6.3-inch VGA screen is used, in such a case the output impedance would increase, and thus we recommend experimental verification for each product type, and that the capacitance values be set such that the liquid crystal drive voltages are stable.

EXTERNAL DIMENSIONS (REFERENCE)

Note: These dimensions are subject to change without notice.



Plastic QFP12-48 pin



EXTERNAL SHAPE OF THE CHIP (SCI7500D0A)

PAD layout

Chip size:	$3.48 mm \times 3.44 mm$
Chip thickness:	$400 \mu m \pm 30 \mu m$
PAD hole size:	$100 \mu m \times 100 \mu m$
Substrate potential:	VDD
DIE number:	F7500D0A

COORDINATES OF RESPECTIVE PAD CENTERS

Unit: µm

PAD No.	PAD name	Х	Y
1	LO	-1431.2	-1554.4
2	L1	-1191.2	
3	L2	-951.2	
4	L3	-711.2	
5	Vss	-471.2	
6	LP	-280.8	
7	FR	-40.8	
8	XFR	199.2	
9	XSLP	439.2	
10	XTST	679.2	
11	AB	919.2	
12	XBB	1159.2	V
13	VL	1574.4	-1264.8
14	C8N		-1024.8
15	VDDy		-784.8
16	C7N		-544.8
17	Vss		-304.8
18	VEE		-64.8
19	C6N		175.2
20	VEM		415.2
21	C5N		655.2
22	HC	•	895.2

			e inter pun
PAD No.	PAD name	Х	Y
23	C5P	1574.4	1135.2
24	-V3B	1235.2	1554.4
25	C1NB	995.2	
26	Vss	755.2	
27	C1PB	475.2	
28	Vdd	235.2	
29	C4N	-4.8	
30	-V2	-244.8	
31	C4P	-484.8	
32	-V3	-724.8	
33	Vss	-964.8	
34	C1N	-1204.8	
35	C2N	-1444.8	V
36	-V3	-1574.4	935.2
37	C2P		655.2
38	VDD		415.2
39	C1P		175.2
40	Vss		-64.8
41	C3N		-304.8
42	V2		-544.8
43	C3P		-1024.8
44	VDD	V	-1264.8

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